



## Material Content Data Sheet



<b>Sales Product Name</b>		TDA21231		<b>Issued</b>		19. January 2018		
<b>MA#</b>		MA001493874						
<b>Package</b>		PG-IQFN-31-2		<b>Weight*</b>		72.53 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.540	2.12	2.12	21230	21230
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.00		48	
	non noble metal	zinc	7440-66-6	0.014	0.02		192	
	non noble metal	iron	7439-89-6	0.279	0.38		3842	
wire	non noble metal	copper	7440-50-8	11.316	15.60	16.00	156013	160095
	non noble metal	copper	7440-50-8	0.099	0.14	0.14	1359	1359
	encapsulation	organic material	carbon black	1333-86-4	0.059	0.08		818
glue	plastics	epoxy resin	-	3.055	4.21		42119	
	inorganic material	silicondioxide	60676-86-0	26.546	36.62	40.91	365989	408926
	leadfinish	non noble metal	tin	7440-31-5	0.986	1.36	1.36	13600
plating	noble metal	silver	7440-22-4	0.054	0.07	0.07	741	741
solder	plastics	epoxy resin	-	0.088	0.12		1218	
	noble metal	silver	7440-22-4	0.265	0.37	0.49	3655	4873
	noble metal	silver	7440-22-4	0.027	0.04		374	
heatspreader	non noble metal	tin	7440-31-5	0.054	0.07		748	
	non noble metal	lead	7439-92-1	1.004	1.38	1.49	13839	14961
	inorganic material	phosphorus	7723-14-0	0.005	0.01		73	
	non noble metal	zinc	7440-66-6	0.021	0.03		292	
heat sink CLIP	non noble metal	iron	7439-89-6	0.424	0.58		5847	
	non noble metal	copper	7440-50-8	17.220	23.74	24.36	237412	243624
	inorganic material	phosphorus	7723-14-0	0.003	0.00		39	
	non noble metal	zinc	7440-66-6	0.011	0.02		157	
*deviation	non noble metal	iron	7439-89-6	0.227	0.31		3134	
	non noble metal	copper	7440-50-8	9.230	12.73	13.06	127261	130591
						Sum in total:	100.00	

**Important Remarks:**

- Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
- Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
- All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com